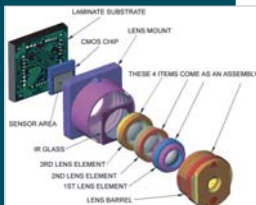
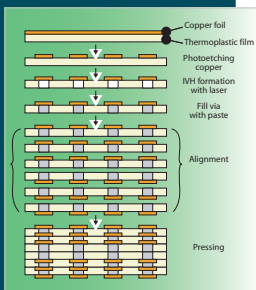
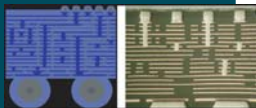
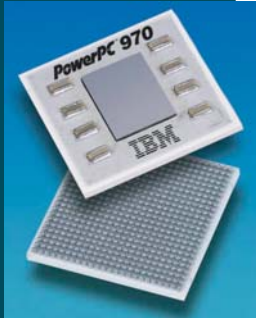


BGA/CSP Development Update Service

Third Quarter, 2004



The third quarterly BGA/CSP update for 2004 features special coverage of lidless packaging trends. A new high-density substrate and flip chip packaging solution, jointly developed by Denso and NEC, is presented. The report also includes a section on packaging trends for camera phones including sensor package types. A special section on the lead-free movement is included. Featured are trends in shipments of solder paste and lead-free solder balls as well as reliability test results with lead-free components. Highlights from the Panasonic FA "Create Show" are also described.

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